CSEAC 半导体设备年会
Semiconductor Equipment Annual Conference

第十三届半导体设备与核心部件及材料展（CSEAC 2025）

The 13th Semiconductor Equipment & Core Components & Materials Exhibition

Booth Plan

芯片振兴·装备先行
Revitalize chips, equipment first

2025年9月4-6日 无锡太湖国际博览中心
September 3-5,2025 Taihu International Expo Center, Wuxi, China

A4馆 封测设备/晶圆制造设备/核心部件及材料展区

Hall A4(2F) Packaging and testing equipment exhibition area/Wafer fabrication exhibition area /Core components and materials exhibition area

A6馆 封测设备/晶圆制造设备/核心部件及材料展区

Hall A6(2F) Packaging and testing equipment exhibition area/Wafer fabrication exhibition area /Core components and materials exhibition area

A1馆 晶圆制造设备展区

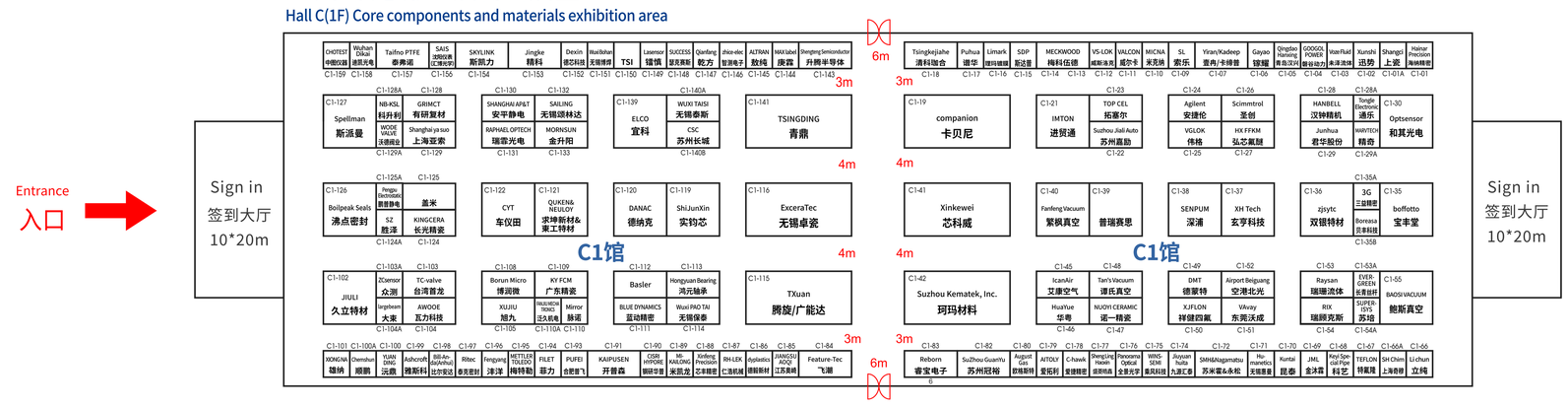
Hall A1(1F) Wafer fabrication exhibition area

A3馆 封测设备展区/晶圆制造设备展区

Hall A3(1F) Packaging and testing equipment exhibition area/Wafer fabrication exhibition area

C1馆 核心部件及材料展区

Hall C(1F) Core components and materials exhibition area

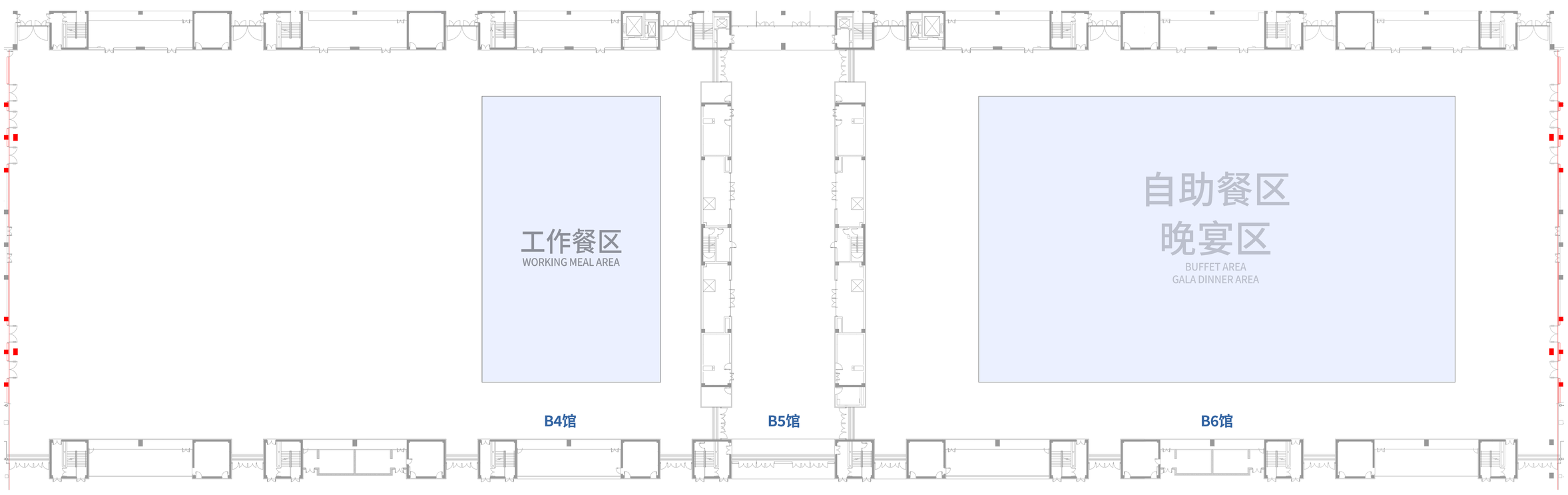


B1馆 核心部件及材料展区

Hall B1(1F) Core components and materials exhibition area

B3馆 晶圆制造设备展区/核心部件及材料展区

Hall B3(1F) Wafer fabrication exhibition area/Core components and materials exhibition area



备注：展位图规划最终解释权归组委会所有